


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM85PLNB1P6	COYA*767MCB7	A	3068	29-10-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	72.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
NAC	6.5x4.4x1	20		
Comment	Package : YA TSSOP 20 BODY 4.4 PITCH 0.65 0087225			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	COYA*767MCB7				6000000.0	1000003.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.005	mg	supplier	die	Silicon (Si)	7440-21-3		1.923	mg	959102	26708
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	3491	97
				supplier	metallization	Copper (Cu)	7440-50-8		0.024	mg	11970	333
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.003	mg	1496	42
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1995	56
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	2993	83
				supplier	Passivation	Silicon Oxide	7631-86-9		0.038	mg	18953	528
LEADFRAME	M-011 Other inorganic materials	36.431	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		34.408	mg	944470	477889
				supplier	ALLOY	Nickel (Ni)	7440-02-0		1.073	mg	29453	14903
				supplier	ALLOY	Silicon (Si)	7440-21-3		0.232	mg	6368	3222
				supplier	ALLOY	Magnesium (Mg)	7439-95-4		0.054	mg	1482	750
				supplier	COATING	Nickel (Ni)	7440-02-0		0.647	mg	17760	8986
				supplier	COATING	Palladium (Pd)	7440-05-3		0.014	mg	384	194
				supplier	COATING	Gold (Au)	7440-57-5		0.003	mg	82	42
DIE ATTACH	M-011 Other inorganic materials	0.848	mg	supplier	GLUE	Silver (Ag)	7440-22-4		0.745	mg	878000	10341
				supplier	GLUE	Isobornyl Methacrylate	7534-94-3		0.042	mg	50000	589
				supplier	GLUE	Urethane Methacrylate Resin	5888-33-5		0.042	mg	50000	589
				supplier	GLUE	Acrylate polymer	87320-05-6		0.017	mg	20000	236
				supplier	GLUE	Epoxyoctahydroxyethyltrimethoxysilane	3388-04-3		0.001	mg	1000	12
				supplier	GLUE	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1000	12
BONDING WIRE	M-011 Other inorganic materials	0.270	mg	supplier	BONDING WIRE	Silver (Ag)	7440-22-4		0.261	mg	965000	3619
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.001	mg	5000	19
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.008	mg	30000	113
ENCAPSULATION	M-011 Other inorganic materials	32.175	mg	supplier	MOLDING COMPOUND	Silica, vitreous	60676-86-0		27.952	mg	868745	388221
				supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		2.364	mg	73464	32829
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		1.576	mg	48976	21886
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.158	mg	4898	2189
FINISHING	M-011 Other inorganic materials	0.271	mg	supplier	MOLDING COMPOUND	Bismuth compound	7440-69-9		0.126	mg	3918	1751
				supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		0.264	mg	974170	3667
				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0.006	mg	22140	83
				supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0.001	mg	3690	14